BC635; BCP54; BCX54

45 V, 1 A NPN medium power transistors

Rev. 07 — 4 June 2007 Product data sheet

1. Product profile

1.1 General description

NPN medium power transistor series.

Table 1. Product overview

Type number[1]	Package			PNP complement
	NXP	JEITA	JEDEC	
BC635[2]	SOT54	SC-43A	TO-92	BC636
BCP54	SOT223	SC-73	-	BCP51
BCX54	SOT89	SC-62	TO-243	BCX51

[1] Valid for all available selection groups.

[2] Also available in SOT54A and SOT54 variant packages (see Section 2).

1.2 Features

- High current
- Two current gain selections
- High power dissipation capability

1.3 Applications

- Linear voltage regulators
- Low side switches
- MOSFET drivers
- Amplifiers

1.4 Quick reference data

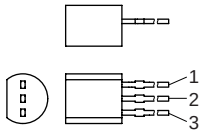
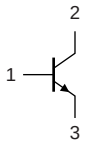
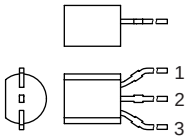
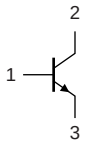
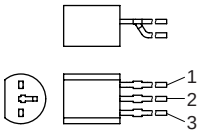
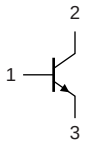
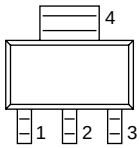
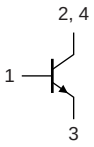
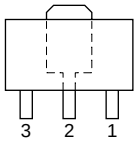
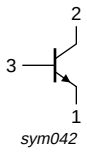
Table 2. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_{CEO}	collector-emitter voltage	open base	-	-	45	V
I_C	collector current		-	-	1	A
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms	-	-	1.5	A
h_{FE}	DC current gain	V_{CE} = 2 V; I_C = 150 mA	63	-	250	
	h_{FE} selection -10	V_{CE} = 2 V; I_C = 150 mA	63	-	160	
	h_{FE} selection -16	V_{CE} = 2 V; I_C = 150 mA	100	-	250	

NXP founded by Philips

2. Pinning information

Table 3. Pinning

Pin	Description	Simplified outline	Symbol
SOT54			
1	base	 001aab347	 sym056
2	collector		
3	emitter		
SOT54A			
1	base	 001aab348	 sym056
2	collector		
3	emitter		
SOT54 variant			
1	base	 001aab447	 sym056
2	collector		
3	emitter		
SOT223			
1	base		 sym016
2	collector		
3	emitter		
4	collector		
SOT89			
1	emitter		 sym042
2	collector		
3	base		

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3. Ordering information

Table 4. Ordering information

Type number[1]	Package		
	Name	Description	Version
BC635[2]	SC-43A	plastic single-ended leaded (through hole) package; 3 leads	SOT54
BCP54	SC-73	plastic surface-mounted package with increased heatsink; 4 leads	SOT223
BCX54	SC-62	plastic surface-mounted package; collector pad for good heat transfer; 3 leads	SOT89

[1] Valid for all available selection groups.

[2] Also available in SOT54A and SOT54 variant packages (see Section 2 and Section 9).

4. Marking

Table 5. Marking codes

Type number	Marking code
BC635	C635
BC635-16	C63516
BCP54	BCP54
BCP54-10	BCP54/10
BCP54-16	BCP54/16
BCX54	BA
BCX54-10	BC
BCX54-16	BD

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5. Limiting values

Table 6. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_{CBO}	collector-base voltage	open emitter		-	45	V
V_{CEO}	collector-emitter voltage	open base		-	45	V
V_{EBO}	emitter-base voltage	open collector		-	5	V
I_C	collector current			-	1	A
I_{CM}	peak collector current	single pulse; $t_p \leq 1$ ms		-	1.5	A
I_{BM}	peak base current	single pulse; $t_p \leq 1$ ms		-	0.2	A
P_{tot}	total power dissipation	$T_{amb} \leq 25$ °C				
	BC635		[1]	-	0.83	W
	BCP54		[1]	-	0.64	W
			[2]	-	0.96	W
	BCX54		[1]	-	0.5	W
			[2]	-	0.85	W
			[3]	-	1.25	W
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			–65	+150	°C
T_{stg}	storage temperature			–65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm^2.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm^2.

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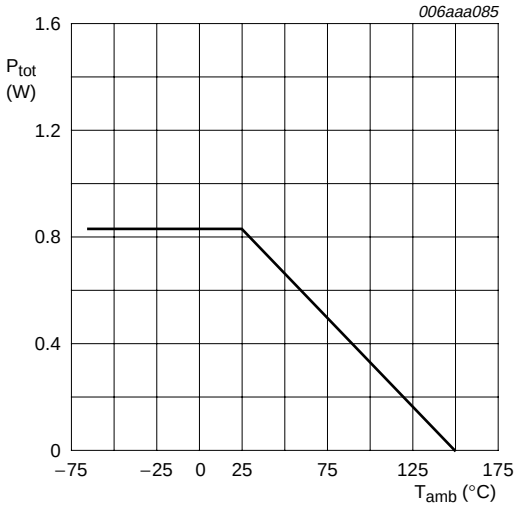
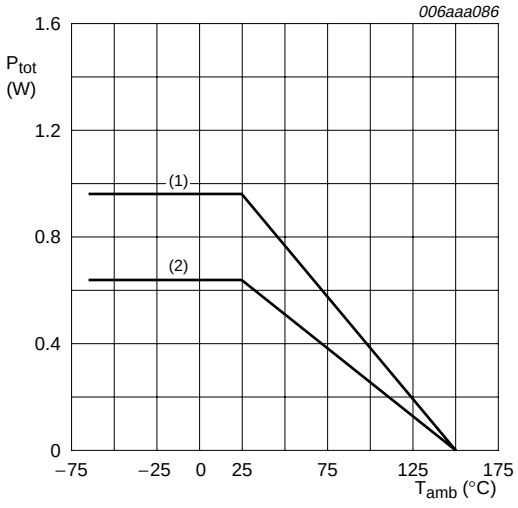


FR4 PCB, standard footprint

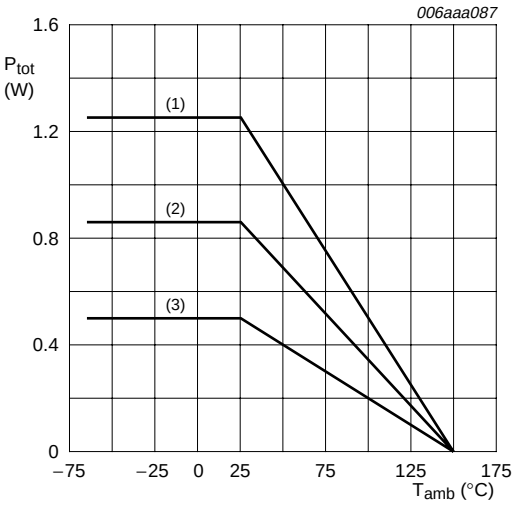
Fig 1. Power derating curve SOT54



(1) FR4 PCB, mounting pad for collector 1 cm^2

(2) FR4 PCB, standard footprint

Fig 2. Power derating curves SOT223



(1) FR4 PCB, mounting pad for collector 6 cm^2

(2) FR4 PCB, mounting pad for collector 1 cm^2

(3) FR4 PCB, standard footprint

Fig 3. Power derating curves SOT89

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6. Thermal characteristics

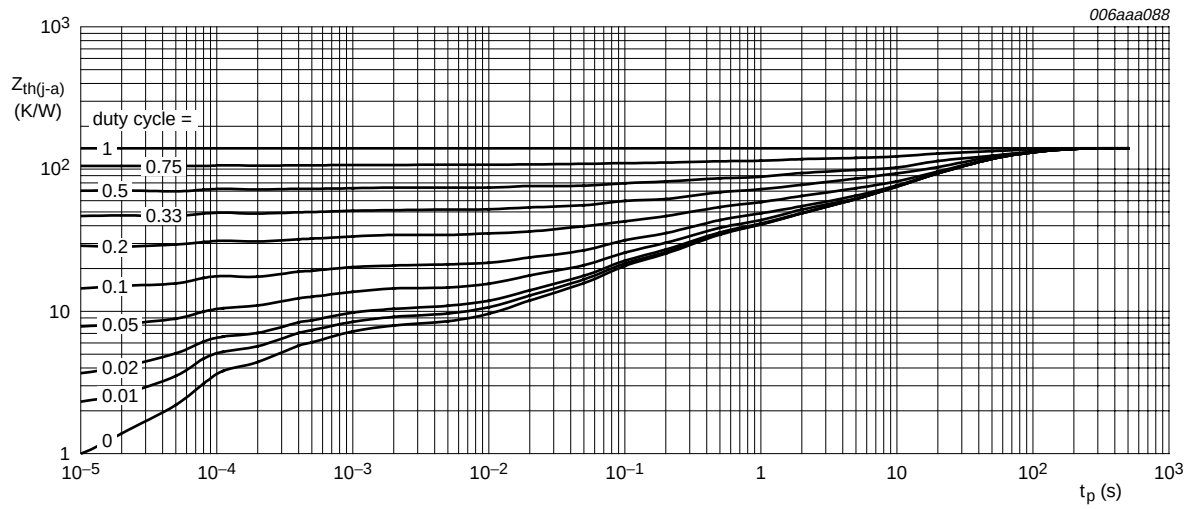
Table 7. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air					
	BC635		[1]	-	-	150	K/W
	BCP54		[1]	-	-	195	K/W
			[2]	-	-	130	K/W
	BCX54		[1]	-	-	250	K/W
			[2]	-	-	145	K/W
			[3]	-	-	100	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point						
	BC635			-	-	40	K/W
	BCP54			-	-	17	K/W
	BCX54			-	-	30	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 1 cm^2.

[3] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for collector 6 cm^2.



FR4 PCB, standard footprint

Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT54; typical values

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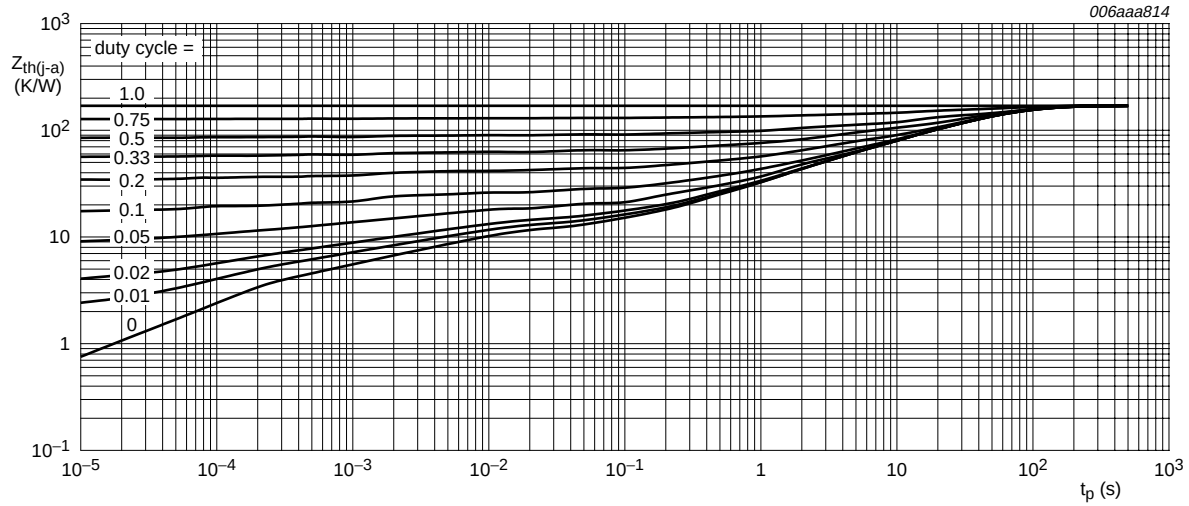
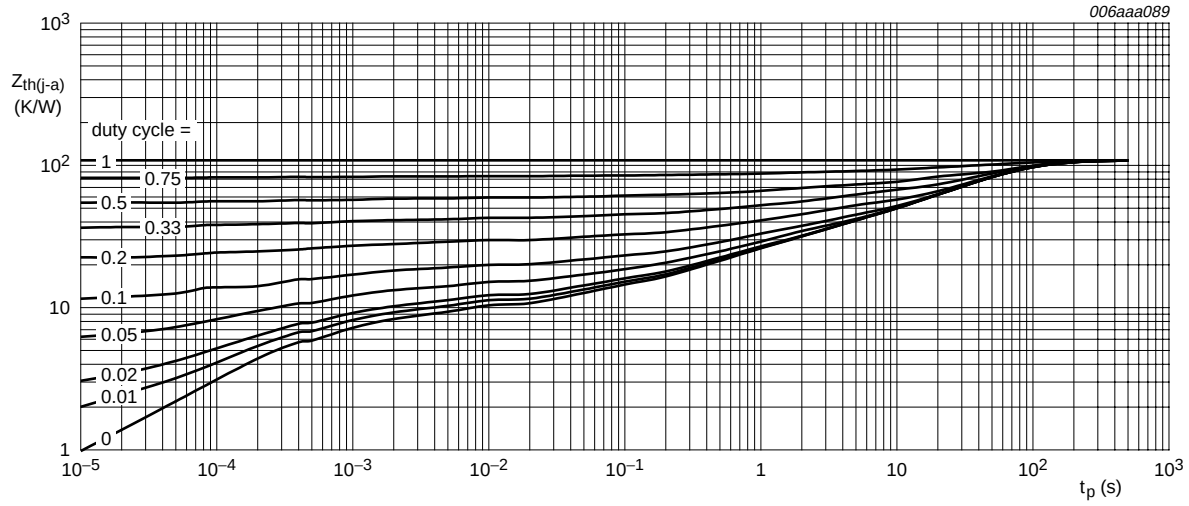


FR4 PCB, standard footprint

Fig 5. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT223; typical values



FR4 PCB, mounting pad for collector 1 cm^2

Fig 6. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT223; typical values

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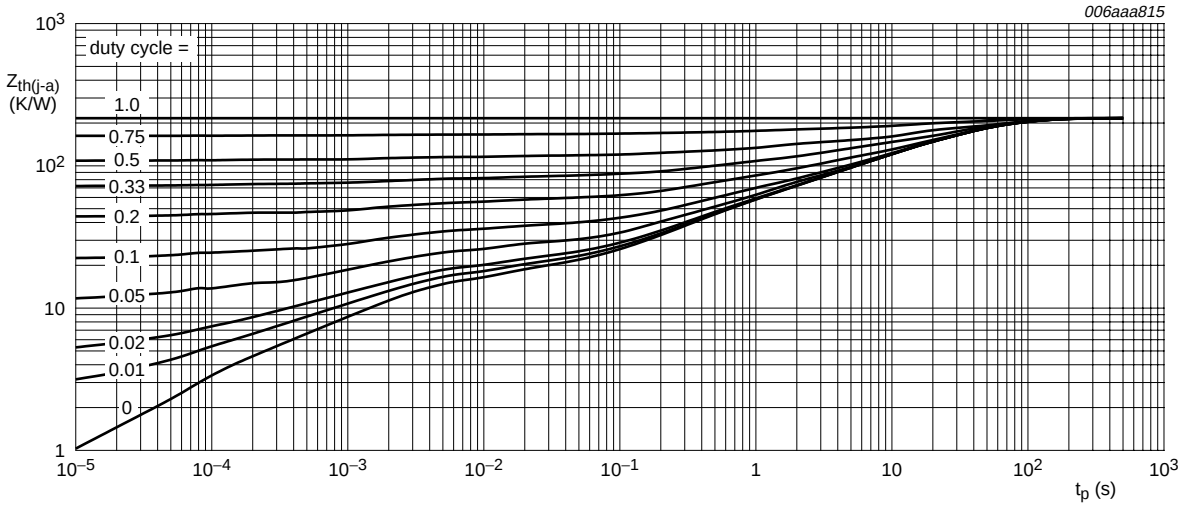
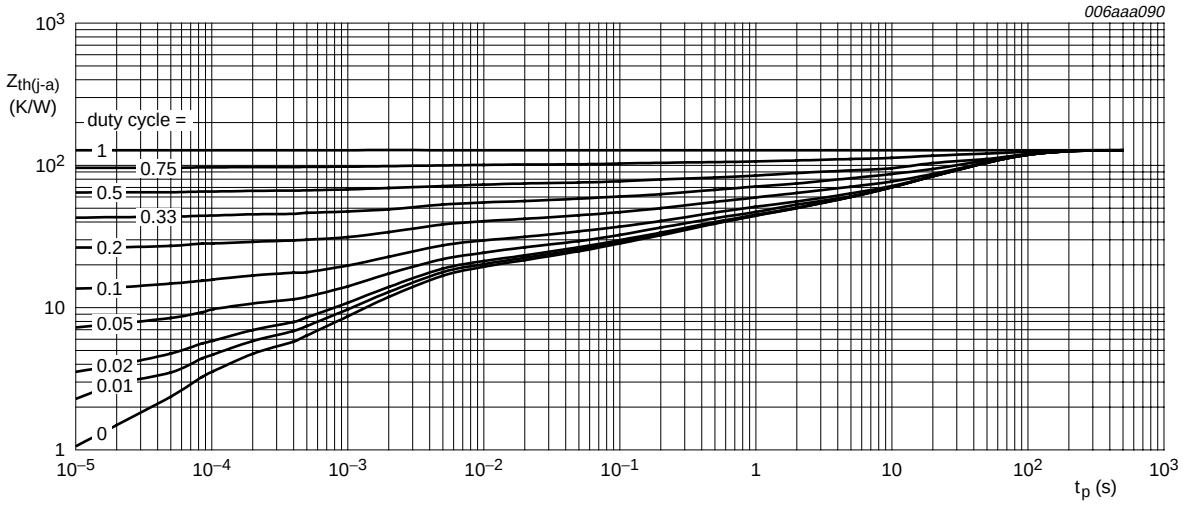


FR4 PCB, standard footprint

Fig 7. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT89; typical values



FR4 PCB, mounting pad for collector 1 cm^2

Fig 8. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT89; typical values

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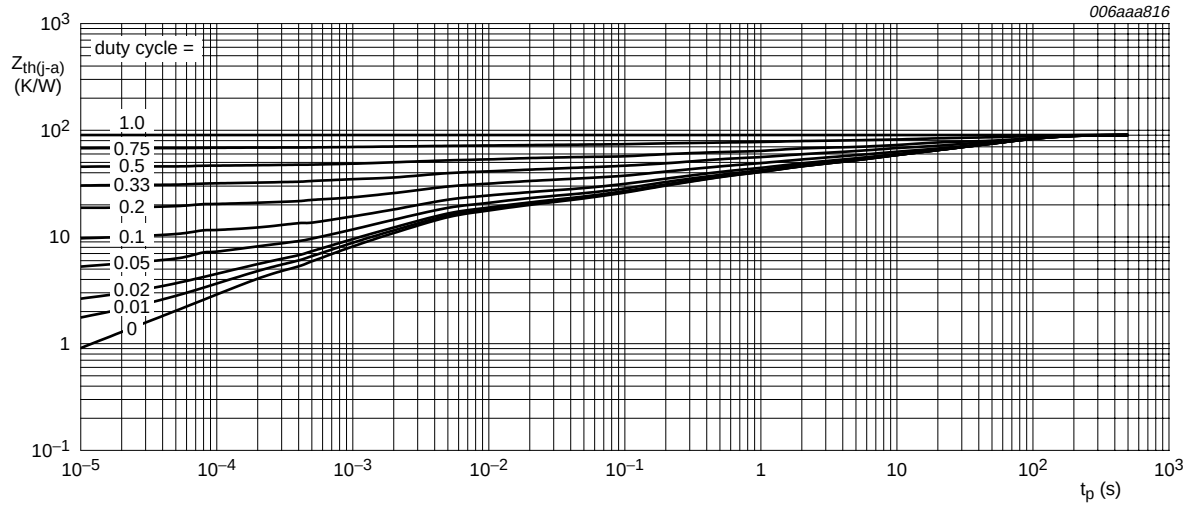

FR4 PCB, mounting pad for collector 6 cm^2

Fig 9. Transient thermal impedance from junction to ambient as a function of pulse duration for SOT89; typical values

7. Characteristics

Table 8. Characteristics

T_{amb} = 25 °C unless otherwise specified.

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
I_{CBO}	collector-base cut-off current	V_{CB} = 30 V; I_E = 0 A		-	-	100	nA
		V_{CB} = 30 V; I_E = 0 A; T_j = 150 °C		-	-	10	µA
I_{EBO}	emitter-base cut-off current	V_{EB} = 5 V; I_C = 0 A		-	-	100	nA
h_{FE}	DC current gain	V_{CE} = 2 V					
		I_C = 5 mA		63	-	-	
		I_C = 150 mA		63	-	250	
		I_C = 500 mA	[1]	40	-	-	
	DC current gain	V_{CE} = 2 V					
	h_{FE} selection -10	I_C = 150 mA		63	-	160	
	h_{FE} selection -16	I_C = 150 mA		100	-	250	
V_{CEsat}	collector-emitter saturation voltage	I_C = 500 mA; I_B = 50 mA	[1]	-	-	500	mV
V_{BE}	base-emitter voltage	V_{CE} = 2 V; I_C = 500 mA	[1]	-	-	1	V
C_c	collector capacitance	V_{CB} = 10 V; I_E = i_e = 0 A; f = 1 MHz		-	6	-	pF
f_T	transition frequency	V_{CE} = 5 V; I_C = 50 mA; f = 100 MHz		100	180	-	MHz

[1] Pulse test: $t_p \leq 300$ µs; $\delta = 0.02$.

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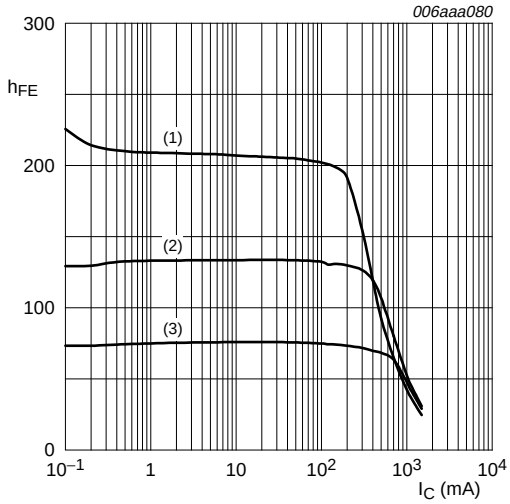


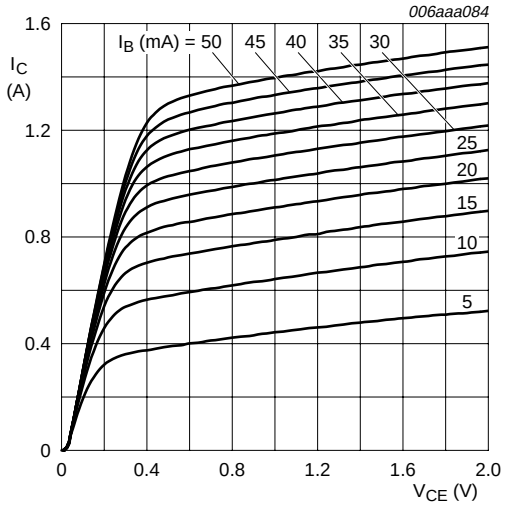
V_{CE} = 2 V

(1) T_{amb} = 150 °C

(2) T_{amb} = 25 °C

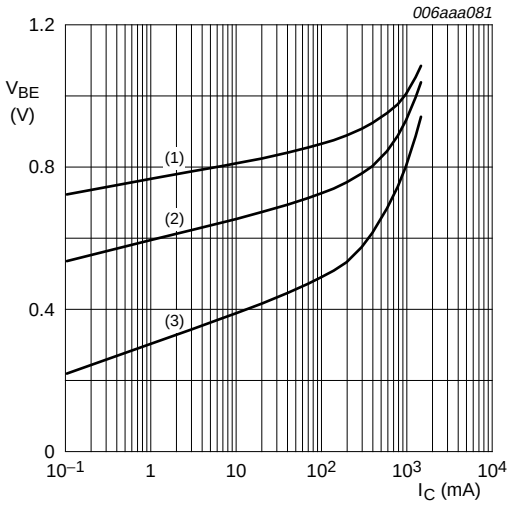
(3) T_{amb} = −55 °C

Fig 10. DC current gain as a function of collector current; typical values



T_{amb} = 25 °C

Fig 11. Collector current as a function of collector-emitter voltage; typical values



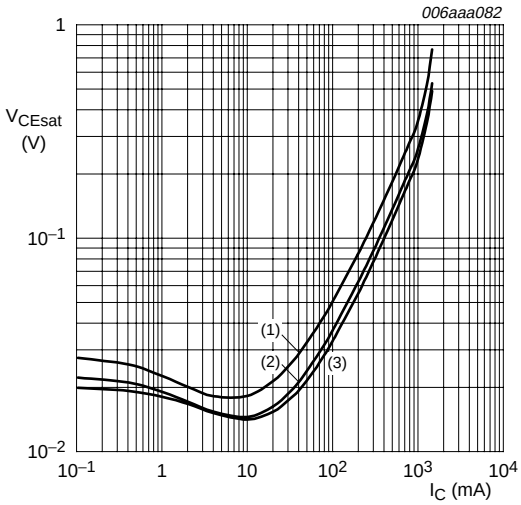
V_{CE} = 2 V

(1) T_{amb} = −55 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = 150 °C

Fig 12. Base-emitter voltage as a function of collector current; typical values



I_C/I_B = 10

(1) T_{amb} = 150 °C

(2) T_{amb} = 25 °C

(3) T_{amb} = −55 °C

Fig 13. Collector-emitter saturation voltage as a function of collector current; typical values

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8. Package outline

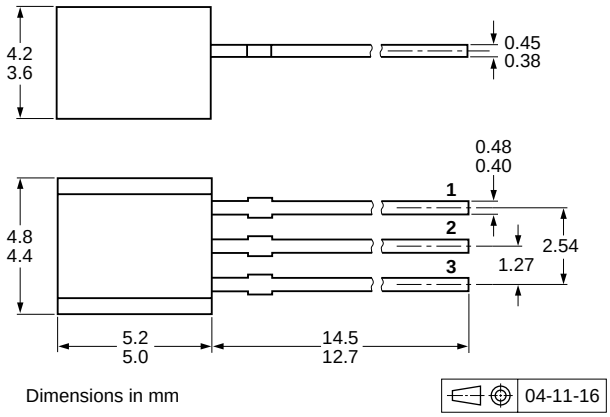

Fig 14. Package outline SOT54 (SC-43A/TO-92)

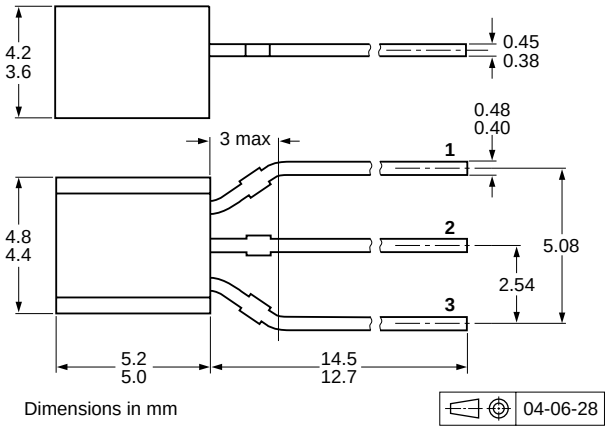

Fig 15. Package outline SOT54A

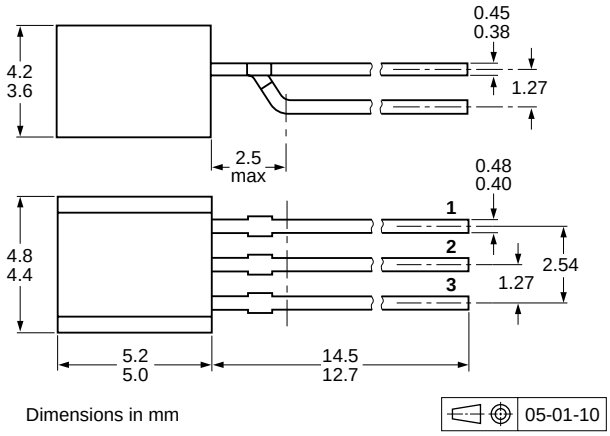

Fig 16. Package outline SOT54 variant

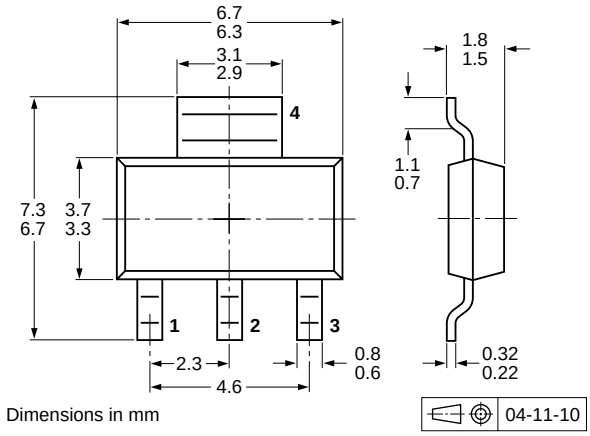

Fig 17. Package outline SOT223 (SC-73)

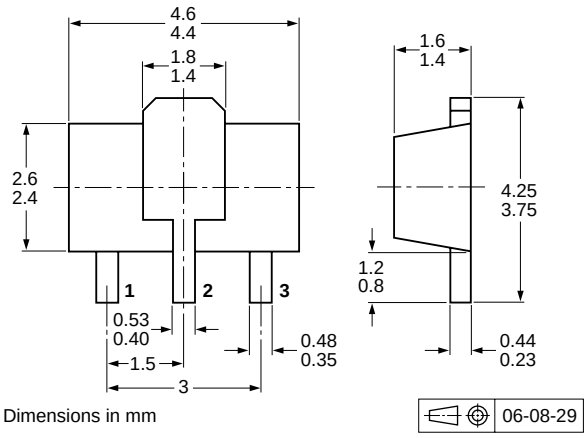

Fig 18. Package outline SOT89 (SC-62/TO-243)

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9. Packing information

Table 9. Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code.[1]

Type number[2]	Package	Description	Packing quantity			
			1000	4000	5000	10000
BC635	SOT54	bulk, straight leads	-	-	-412	-
	SOT54A	tape and reel, wide pitch	-	-	-	-116
		tape ammopack, wide pitch	-	-	-	-126
	SOT54 variant	bulk, delta pinning	-	-	-112	-
BCP54	SOT223	8 mm pitch, 12 mm tape and reel	-115	-135	-	-
BCX54	SOT89	8 mm pitch, 12 mm tape and reel; T1 [3]	-115	-135	-	-
		8 mm pitch, 12 mm tape and reel; T3 [4]	-120	-	-	-

[1] For further information and the availability of packing methods, see Section 12.

[2] Valid for all available selection groups.

[3] T1: normal taping

[4] T3: 90° rotated taping

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10. Revision history

Table 10. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
BC635_BCP54_BCX54_7	20070604	Product data sheet	-	BC635_BCP54_BCX54_6
Modifications:	• Table 1 “Product overview”: amended • Section 1.2 “Features”: amended • Section 1.3 “Applications”: amended • Table 2 “Quick reference data”: I_C parameter redefined to collector current • Table 2 “Quick reference data”: I_{CM} condition added • Figure 2 and 3: amended • Table 6 “Limiting values”: I_C parameter redefined to collector current • Table 6 “Limiting values”: I_{CM} condition added • Table 6 “Limiting values”: P_{tot} values for BCP54 and BCX54 adapted • Table 7 “Thermal characteristics”: $R_{th(j-a)}$ values for BCP54 and BCX54 rounded • Figure 4: Z_{th} redefined to $Z_{th(j-a)}$ transient thermal impedance from junction to ambient • Figure 4: t_p parameter redefined to pulse duration • Figure 5: added • Figure 6: Z_{th} redefined to $Z_{th(j-a)}$ transient thermal impedance from junction to ambient • Figure 6: t_p parameter redefined to pulse duration • Figure 7: added • Figure 8: Z_{th} redefined to $Z_{th(j-a)}$ transient thermal impedance from junction to ambient • Figure 8: t_p parameter redefined to pulse duration • Figure 9: added • Figure 11: amended • Table 9 “Packing methods”: new packing method for BCX54 added • Section 11 “Legal information”: updated			
BC635_BCP54_BCX54_6	20050225	Product data sheet	CPCN200405029	BC635_637_639_4 BCP54_55_56_5 BCX54_55_56_4
BC635_637_639_4	20011010	Product specification	-	BC635_637_639_3
BCP54_55_56_5	20030206	Product specification	-	BCP54_55_56_4
BCX54_55_56_4	20011010	Product specification	-	BCX54_55_56_3

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11. Legal information

11.1 Data sheet status

Document status[1][2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

[3] The product status of device(s) described in this document may have changed since this document was published and may differ in case of multiple devices. The latest product status information is available on the Internet at URL http://www.nxp.com.

11.2 Definitions

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